MSKSEMI















ESD

TVS

TSS

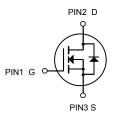
MOV

GDT

PLED

Broduct data sheet





N-Channel MOSFET

TO-252

Description

The AOD424-MS uses advanced trench technology to provide excellent R_{DS(ON)}, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

 $V_{DS} = 20V I_{D} = 60 A$

 $R_{DS(ON)}$ < 6.5m Ω @ V_{GS} =4.5V

Application

Battery protection

Load switch

Uninterruptible power supply

Absolute Maximum Ratings (Tc=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _G s	±12	V
Drain Current-Continuous	lο	60	Α
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	42	Α
Pulsed Drain Current	Івм	210	Α
Maximum Power Dissipation	P _D	60	W
Derating factor		0.48	W/°C
Single pulse avalanche energy (Note 5)	Eas	200	mJ
Operating Junction and Storage Temperature Range	Тл,Тѕтс	-55 To 150	$^{\circ}$
Thermal Resistance,Junction-to-Case ^(Note 2)	Rejc	2.1	°C/W



Electrical Characteristics (T_C=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	20	ı	-	V
Zero Gate Voltage Drain Current	Ipss	V _{DS} =20V,V _{GS} =0V	-	-	1	μΑ
Gate-Body Leakage Current	Igss	V _{GS} =±12V,V _{DS} =0V	-	-	±100	nA
Gate Threshold Voltage	V _G S(th)	V _{DS} =V _{GS} ,I _D =250μA	0.5	0.75	1.0	V
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =20 A	-	5.5	7	mΩ
	Rds(on)	V _{GS} =2.5V, I _D =15A		6.2	9	mΩ
Forward Transconductance	g FS	V _{DS} =10V,I _D =20A	15	-	-	S
Input Capacitance	C _{lss}		-	2000	-	PF
Output Capacitance	Coss	V _{DS} =10V,V _{GS} =0V,	-	500	-	PF
Reverse Transfer Capacitance	Crss	F=1.0MHz	-	200	-	PF
Turn-on Delay Time	t _{d(on)}		-	6.4	-	nS
Turn-on Rise Time	t _r	$V_{DD}=10V,I_{D}=2A,R_{L}=1\Omega$	-	17.2	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =4.5V, R_{G} =3 Ω	-	29.6	-	nS
Turn-Off Fall Time	t _f		-	16.8	-	nS
Total Gate Charge	Qg		-	27		nC
Gate-Source Charge	Qgs	V _{DS} =10V,I _D =20A,	-	6.5		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V	-	6.4		nC
Diode Forward Voltage (Note 3)	Vsp	V _{GS} =0V,I _S =10A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	60	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, IF = 20A	-	25	-	nS
Reverse Recovery Charge	Qrr	di/dt = 100A/μs ^(Note3)	-	24	-	nC
Forward Turn-On Time	ton	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production
- **5.** Eas condition : Tj=25 $^{\circ}$ C,VDD=10V,VG=10V,L=0.5mH,Rg=25 Ω ,





Typical Electrical and Thermal Characteristics (Curves)

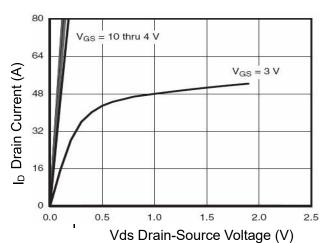


Figure 1 Output Characteristics

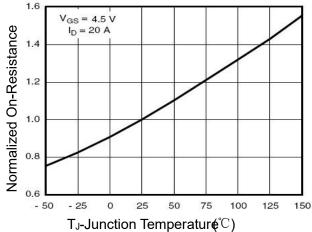
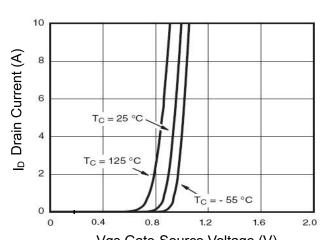


Figure 4 Rdson-JunctionTemperature



Vgs Gate-Source Voltage (V) Figure 2 Transfer Characteristics

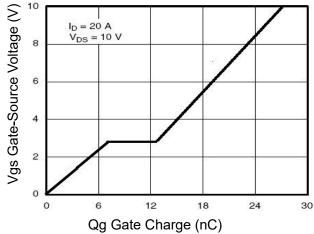


Figure 5 Gate Charge

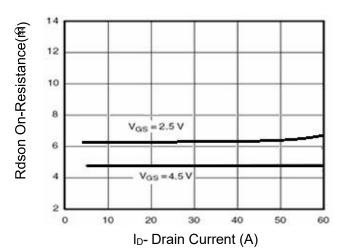


Figure 3 Rdson- Drain Current

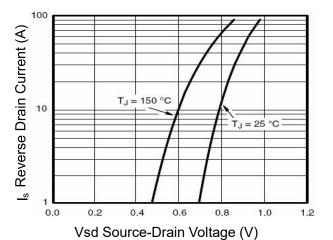
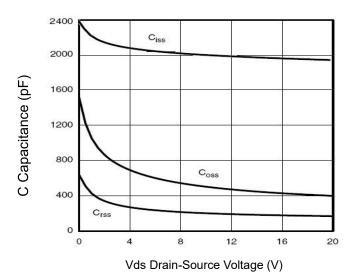


Figure 6 Source- Drain Diode Forward

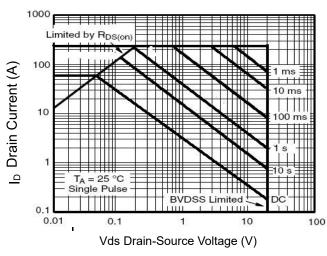




60 50 Power Dissipation (W) 40 30 20 10 0 25 50 0 150 T_J-Junction Temperature (°C)

Figure 7 Capacitance vs Vds

Figure 9 Power De-rating



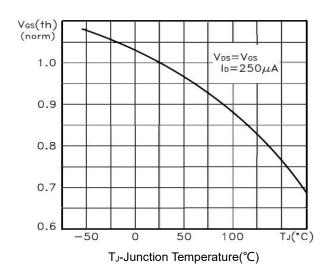
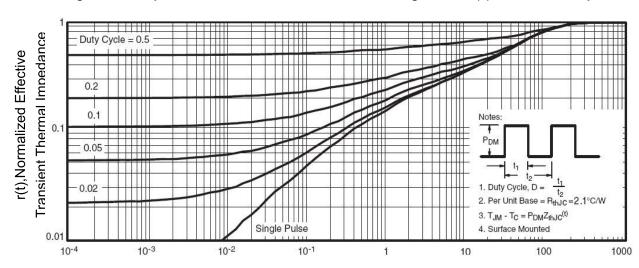


Figure 8 Safe Operation Area

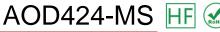
Figure 10 V_{GS(th)} vs Junction Temperature

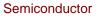


Square Wave Pluse Duration(sec)

Figure 11 Normalized Maximum Transient Thermal Impedance

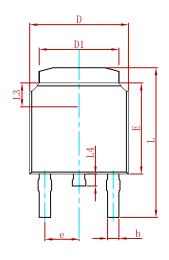


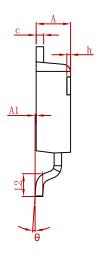


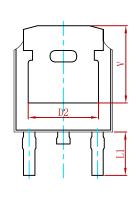




PACKAGE MECHANICAL DATA

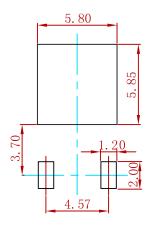






Cumbal	Dimensions In Millimeters		Dimension	s In Inches
Symbol	Min.	Max.	Min.	Max.
Α	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
С	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190	REF.
E	6.000	6.200	0.236	0.244
е	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900	REF.	0.114	REF.
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063	REF.
L4	0.600	1.000	0.024	0.039
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250	REF.	0.207	REF.

Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
AOD424-MS	TO-252	2500



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BSS340NWH6327XTSA1 MCM3400A-TP DMTH10H4M6SPS-13 IRF40SC240ARMA1 IPS60R1K0PFD7SAKMA1

IPS60R360PFD7SAKMA1 IPS60R600PFD7SAKMA1